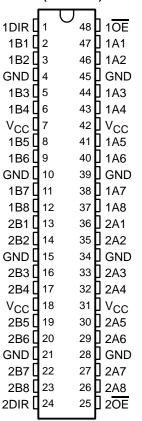
SCES331A - APRIL 2000 - REVISED APRIL 2002

- State-of-the-Art Advanced BiCMOS
 Technology (ABT) Widebus™ Design for
 2.5-V and 3.3-V Operation and Low
 Static-Power Dissipation
- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 2.3-V to 3.6-V V_{CC})
- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- High Drive
 - A Port = -12/12 mA at 3.3-V V_{CC}
 - B port = -32/64 mA at 3.3-V V_{CC}
- I_{off} and Power-Up 3-State Support Hot Insertion
- Use Bus Hold on Data Inputs in Place of External Pullup/Pulldown Resistors to Prevent the Bus From Floating
- A-Port Outputs Have Equivalent 30-Ω
 Series Resistors, So No External Resistors
 Are Required
- Flow-Through Architecture Facilitates
 Printed Circuit Board Layout
- Distributed V_{CC} and GND Pins Minimize High-Speed Switching Noise
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II

SN54ALVTH162245 . . . WD PACKAGE SN74ALVTH162245 . . . DGG, DGV, OR DL PACKAGE (TOP VIEW)



description

The 'ALVTH162245 devices are 16-bit (dual-octal) noninverting 3-state transceivers designed for 2.5-V or 3.3-V V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

These devices can be used as two 8-bit transceivers or one 16-bit transceiver. They allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can be used to disable the device so that the buses are effectively isolated.

The A-port outputs, which are designed to source or sink up to 12 mA, include equivalent $30-\Omega$ series resistors to reduce overshoot and undershoot.

These devices are fully specified for hot-insertion applications using I_{off} and power-up 3-state. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Widebus is a trademark of Texas Instruments.

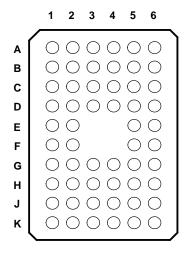


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description (continued)

When V_{CC} is between 0 and 1.2 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.2 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

SN74ALVTH162245 . . . GQL PACKAGE (TOP VIEW)



terminal assignments

	1	2	3	4	5	6
Α	1DIR	NC	NC	NC	NC	1OE
В	1B2	1B1	GND	GND	1A1	1A2
С	1B4	1B3	Vcc	Vcc	1A3	1A4
D	1B6	1B5	GND	GND	1A5	1A6
Е	1B8	1B7			1A7	1A8
F	2B1	2B2			2A2	2A1
G	2B3	2B4	GND	GND	2A4	2A3
Н	2B5	2B6	VCC	VCC	2A6	2A5
J	2B7	2B8	GND	GND	2A8	2A7
K	2DIR	NC	NC	NC	NC	2 <mark>OE</mark>

NC - No internal connection

ORDERING INFORMATION

TA	T _A PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	SSOP – DL	Tape and reel	SN74ALVTH162245LR	ALVTH162245
–40°C to 85°C	TSSOP – DGG	Tape and reel	SN74ALVTH162245GR	ALVTH162245
-40 C to 65 C	TVSOP – DGV	Tape and reel	SN74ALVTH162245VR	VT2245
	VFBGA – GQL	Tape and reel	SN74ALVTH162245QR	
–55°C to 125°C	CFP – WD Tube		SNJ54ALVTH162245WD	SNJ54ALVTH162245WD

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

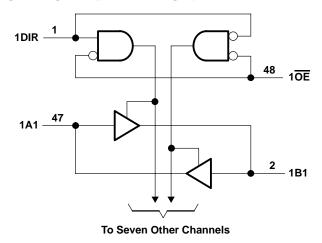
FUNCTION TABLE (each 8-bit section)

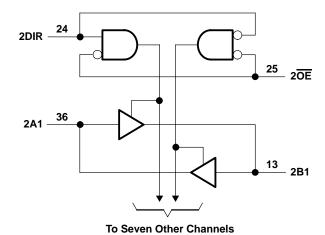
INP	UTS	OPERATION			
OE	DIR	OPERATION			
L	L	B data to A bus			
L	Н	A data to B bus			
Н	Χ	Isolation			



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logic diagram (positive logic)





Pin numbers shown are for the DGG, DGV, DL, and WD packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

. −0.5 V to 4.6 V
–0.5 V to 7 V
–0.5 V to 7 V
–0.5 V to 7 V
96 mA
128 mA
–48 mA
–64 mA
±100 mA
–50 mA
–50 mA
70°C/W
58°C/W
63°C/W
42°C/W
–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.



NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

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recommended operating conditions, V_{CC} = 2.5 V \pm 0.2 V (see Note 3)

			SN54	ALVTH1	62245	SN74	ALVTH1	62245	UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	UNII
VCC	Supply voltage		2.3		2.7	2.3		2.7	V
VIH	High-level input voltage		1.7			1.7			V
V _{IL}	Low-level input voltage				0.7			0.7	V
VI	Input voltage		0	VCC	5.5	0	VCC	5.5	V
lau	High-level output current (A port)			À	-6			-8	mΑ
ЮН	High-level output current (B port)			200	-6			-8	IIIA
	Low-level output current (A port)			6	6			12	
lou	Low-level output current (B port)			3	6			8	mA
IOL	Low-level output current; current duty cycle \leq 50%; f \geq 1 kHz (B port)		PA) ·	18			24	ША
Δt/Δν	Input transition rise or fall rate	Outputs enabled			10			10	ns/V
Δt/ΔV _{CC}	Power-up ramp rate		200			200			μs/V
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

recommended operating conditions, $V_{\mbox{\footnotesize{CC}}}$ = 3.3 V \pm 0.3 V (see Note 3)

			SN54	ALVTH1	62245	SN74/	ALVTH1	62245	UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	UNIT
VCC	Supply voltage		3		3.6	3		3.6	V
VIH	High-level input voltage		2			2			V
V _{IL}	Low-level input voltage				0.8			0.8	V
VI	Input voltage		0	Vcc	5.5	0	Vcc	5.5	V
1	High-level output current (A port)			7/2	-8			-12	mA
ЮН	High-level output current (B port)			72	-24			-32	IIIA
	Low-level output current (A port)			5	8			12	
lou	Low-level output current (B port)			2	24			32	mA
lOL	Low-level output current; current duty cycle \leq 50%; f \geq 1 kHz (B port)		PA) ·	48			64	ША
Δt/Δν	Input transition rise or fall rate	Outputs enabled			10			10	ns/V
Δt/ΔV _{CC}	Power-up ramp rate		200			200			μs/V
T _A	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

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electrical characteristics over recommended operating free-air temperature range, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted)

D/	ARAMETER	TEST CONDITIONS		SN54	ALVTH1	62245	SN74ALVTH162245		UNIT	
P#	ARAWETER	1551 C	UNDITIONS	MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNII
٧ıK		$V_{CC} = 2.3 \text{ V},$	I _I = -18 mA			-1.2			-1.2	V
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V},$	I _{OH} = -100 μA	V _{CC} -0.	2		VCC-0	.2		
	A port	V _{CC} = 2.3 V	$I_{OH} = -6 \text{ mA}$	1.7						
\/a		vCC = 2.3 v	$I_{OH} = -8 \text{ mA}$				1.7			V
VOH		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V},$	$I_{OH} = -100 \mu A$	V _{CC} -0.	2		VCC-0	.2		V
	B port	V _{CC} = 2.3 V	$I_{OH} = -6 \text{ mA}$	1.7						
		V(C = 2.3 V	$I_{OH} = -8 \text{ mA}$				1.7			
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V},$	I _{OL} = 100 μA			0.2			0.2	
	A port	V _{CC} = 2.3 V	$I_{OL} = 6 \text{ mA}$			0.4				
		V(C = 2.3 V	$I_{OL} = 12 \text{ mA}$						0.4	V
VOL		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V},$	I _{OL} = 100 μA			₹ 0.2			0.2	
VOL			$I_{OL} = 6 \text{ mA}$		Š	0.4				V
	B port	V _{CC} = 2.3 V	$I_{OL} = 8 \text{ mA}$		<u></u>		0.4			
		V(C = 2.5 V	$I_{OL} = 18 \text{ mA}$		1	0.5				
			$I_{OL} = 24 \text{ mA}$		3				0.5	
	Control inputs	$V_{CC} = 2.7 \text{ V},$	V _I = GND		5	±1			±1	
	Control inputs	$V_{CC} = 0 \text{ or } 2.7 \text{ V},$	V _I = 5.5 V	Q		10			10	
lį	A or B ports $V_{CC} = 2.7 \text{ V}$		V _I = 5.5 V			20			20	μΑ
		$V_{CC} = 2.7 \text{ V}$	$V_I = V_{CC}$			1			1	
			V _I = 0			- 5			- 5	
l _{off}		$V_{CC} = 0$,	V_I or $V_O = 0$ to 4.5 V						±100	μΑ
I _{BHL} ‡		$V_{CC} = 2.3 \text{ V},$	V _I = 0.7 V		115			115		μΑ
I _{BHH} §		$V_{CC} = 2.3 \text{ V},$	V _I = 1.7 V		-10			-10		μΑ
IBHLO		$V_{CC} = 2.7 \text{ V},$	$V_I = 0$ to V_{CC}	300			300			μΑ
Івннс) [#]	$V_{CC} = 2.7 \text{ V},$	$V_I = 0$ to V_{CC}	-300			-300			μΑ
ΙΕΧ		$V_{CC} = 2.3 \text{ V},$	$V_0 = 5.5 \text{ V}$			125			125	μΑ
IOZ(PI	J/PD) ^ጵ	$V_{CC} \le 1.2 \text{ V}, V_{O} = \frac{0.5}{\text{OE}} \text{ V}$ V _I = GND or V _{CC} , $\overline{\text{OE}}$ =	/ to V _{CC} , don't care			±100			±100	μΑ
		V _{CC} = 2.7 V,	Outputs high		0.04	0.1		0.04	0.1	
ICC		$I_{O} = 0$,	Outputs low		2.3	4.5		2.3	4.5	mA
		$V_I = V_{CC}$ or GND	Outputs disabled		0.04	0.1		0.04	0.1	
Ci		V _{CC} = 2.5 V,	V _I = 2.5 V or 0		3.5			3.5		pF
C _{io}		$V_{CC} = 2.5 \text{ V},$	V _O = 2.5 V or 0		8			8		pF

[†] All typical values are at $V_{CC} = 2.5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



[‡] The bus-hold circuit can sink at least the minimum low sustaining current at V_{IL} max. I_{BHL} should be measured after lowering V_{IN} to GND and then raising it to V_{IL} max.

[§] The bus-hold circuit can source at least the minimum high sustaining current at V_{IH} min. I_{BHH} should be measured after raising V_{IN} to V_{CC} and then lowering it to V_{IH} min.

 $[\]P$ An external driver must source at least IBHLO to switch this node from low to high.

[#]An external driver must sink at least IBHHO to switch this node from high to low.

Current into an output in the high state when VO > VCC

^{*}High-impedance state during power up or power down

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electrical characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted)

DA	DAMETED	TEST OF	TEST CONDITIONS		ALVTH1	62245	SN74ALVTH162245		UNIT	
PAI	RAMETER	lesi co	DNDITIONS	MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNII
٧ıK		V _{CC} = 3 V,	I _I = -18 mA			-1.2			-1.2	V
		$V_{CC} = 3 \text{ V to } 3.6 \text{ V},$	I _{OH} = -100 μA	V _{CC} -0	.2		VCC-0	.2		
	A port	V _{CC} = 3 V	$I_{OH} = -8 \text{ mA}$	2						
\/a		ACC = 2 A	$I_{OH} = -12 \text{ mA}$				2			V
VOH		$V_{CC} = 3 \text{ V to } 3.6 \text{ V},$	I _{OH} = -100 μA	V _{CC} -0	.2		VCC-0	.2		V
	B port	VCC = 3 V	$I_{OH} = -24 \text{ mA}$	2						
		VCC = 3 V	$I_{OH} = -32 \text{ mA}$				2			
		$V_{CC} = 3 \text{ V to } 3.6 \text{ V},$	I _{OL} = 100 μA			0.2			0.2	
	A port	VCC = 3 V	$I_{OL} = 8 \text{ mA}$?				
	VCC = 3 V	$I_{OL} = 12 \text{ mA}$						8.0		
VOL		$V_{CC} = 3 \text{ V to } 3.6 \text{ V},$	I _{OL} = 100 μA			0.2			0.2	V
VOL			$I_{OL} = 24 \text{ mA}$			0.5				V
	B port	V _{CC} = 3 V	$I_{OL} = 32 \text{ mA}$			3			0.5	
		VCC = 3 V	$I_{OL} = 48 \text{ mA}$	0.55						
			$I_{OL} = 64 \text{ mA}$		Q.				0.55	
	Control inputs	$V_{CC} = 3.6 \text{ V},$	$V_I = V_{CC}$ or GND		6	±1			±1	μА
	Control inputs	$V_{CC} = 0 \text{ or } 3.6 \text{ V},$	V _I = 5.5 V		20	10			10	
lį			V _I = 5.5 V	8	,	20			20	
	A or B ports	ports $V_{CC} = 3.6 \text{ V}$	$V_I = V_{CC}$	4		1			1	
			V _I = 0			- 5			– 5	
I _{off}		$V_{CC} = 0$,	V_I or $V_O = 0$ to 4.5 V						±100	μΑ
I _{BHL} ‡		$V_{CC} = 3 V$,	V _I = 0.8 V	75			75			μΑ
I _{BHH} §		$V_{CC} = 3 V$,	V _I = 2 V	-75			-75			μΑ
IBHLO		$V_{CC} = 3.6 \text{ V},$	$V_I = 0$ to V_{CC}	500			500			μΑ
Івнно [‡]	#	$V_{CC} = 3.6 \text{ V},$	$V_I = 0$ to V_{CC}	-500			-500			μΑ
{IEX}		$V{CC} = 3 V$,	$V_0 = 5.5 \text{ V}$			125			125	μΑ
IOZ(PU	/PD) [*]	$V_{CC} \le 1.2 \text{ V}, V_{O} = \frac{0.5}{\text{OE}} \text{ V}$ V _I = GND or V _{CC} , $\overline{\text{OE}}$ =	' to V _{CC} , don't care			±100			±100	μА
		V _{CC} = 3.6 V,	Outputs high		0.07	0.1		0.07	0.1	\Box
ICC		$I_{O} = 0$,	Outputs low		3.2	5		3.2	5	mA
		$V_I = V_{CC}$ or GND	Outputs disabled		0.07	0.1		0.07	0.1	
ΔICC	-	V _{CC} = 3 V to 3.6 V, One Other inputs at V _{CC} or C			_	0.2		_	0.2	mA
C _i		V _{CC} = 3.3 V,	V _I = 3.3 V or 0		3.5			3.5		pF
C _{io}		V _{CC} = 3.3 V,	V _O = 3.3 V or 0		8			8		pF
	al valuas are at \	/cc = 3.3 V. T _A = 25°C.		•			•	-		

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[☐] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.



[‡]The bus-hold circuit can sink at least the minimum low sustaining current at V_{IL} max. I_{BHL} should be measured after lowering V_{IN} to GND and then raising it to V_{IL} max.

[§] The bus-hold circuit can source at least the minimum high sustaining current at V_{IH} min. I_{BHH} should be measured after raising V_{IN} to V_{CC} and then lowering it to V_{IH} min.

 $[\]P$ An external driver must source at least IBHLO to switch this node from low to high.

[#]An external driver must sink at least I_{BHHO} to switch this node from high to low.

Current into an output in the high state when VO > VCC

^{*}High-impedance state during power up or power down

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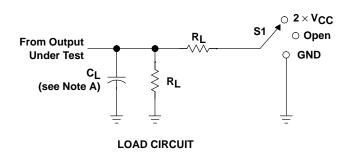
switching characteristics over recommended operating free-air temperature range, C_L = 30 pF, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	SN54ALV	TH162245	SN74ALV	TH162245	UNIT	
PARAMETER	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	UNII	
t _{PLH}	А	В	0.3	3.6	0.3	3.6	no	
t _{PHL}	Α	Ь	0.5	3.5	0.5	3.5	ns	
t _{PLH}	В	Α	1.1	4.3	1.1	4.3	20	
t _{PHL}	Ь	A	1.1	3.8	1.1	3.8	ns	
^t PZH	ŌĒ	Α	2	5.6	2	5.6	20	
^t PZL	OE	A	1.8	4.4	1.8	4.4	ns	
^t PZH	ŌĒ	В	1.5	5.1	1.5	5.1	ne	
^t PZL	OE	Ь	1.5	4.1	1.5	4.1	ns	
^t PHZ	ŌĒ	А	1.9	4.9	1.9	4.9	ns	
t _{PLZ}	OE	^	1.5	4.3	1.5	4.3	115	
t _{PHZ}	ŌĒ	В	1.9	4.8	1.9	4.8	ns	
t _{PLZ}	OE .		1.5	4.1	1.5	4.1	115	

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 2)

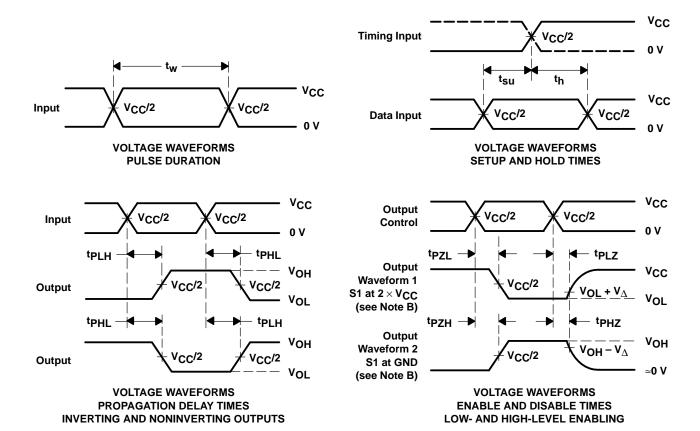
PARAMETER	FROM	то	SN54ALV	TH162245	SN74ALV	TH162245	LINUT
PARAMETER	(INPUT)	(OUTPUT)	MIN	MIN MAX		MAX	UNIT
^t PLH	A	В	0.5	3.1	0.5	3.1	ne
^t PHL		Б	0.5	3	0.5	3	ns
^t PLH	В	А	1	3.7	1	3.7	nc
^t PHL]	A	1	3.4	1	3.4	ns
^t PZH	ŌĒ	А	1.4	4.7	1.4	4.7	no
^t PZL] UE	^	1.4	3.9	1.4	3.9	ns
^t PZH	- OE	В	1,5	3.8	1	3.8	ns
^t PZL		В	0.7	3.4	0.7	3.4	115
^t PHZ	ŌĒ	А	2.4	5	2.4	5	ns
^t PLZ]		2.6	4.9	2.6	4.9	113
^t PHZ	ŌĒ	В	2.4	4.7	2.4	4.7	ne
^t PLZ]	В	2.3	4.8	2.3	4.8	ns

PARAMETER MEASUREMENT INFORMATION



TEST	S1
tPLH/tPHL	Open
tPLZ/tPZL	2×V _{CC}
tPHZ/tPZH	GND

VCC	CL	RL	$v_{\scriptscriptstyle\Delta}$
2.5 V ±0.2 V	30 pF	500 Ω	0.15 V
3.3 V ±0.3 V	50 pF	500 Ω	0.3 V



NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq 2$ ns. $t_f \leq 2$ ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms







com 18-Sep-2008

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74ALVTH162245DLG4	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVTH162245GRE4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVTH162245GRG4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVTH162245LRG4	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVTH162245VRE4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVTH162245VRG4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVTH162245DL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVTH162245GR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVTH162245LR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVTH162245VR	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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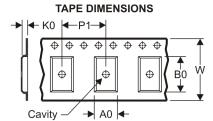
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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





		Dimension designed to accommodate the component width
		Dimension designed to accommodate the component length
P	〈 0	Dimension designed to accommodate the component thickness
		Overall width of the carrier tape
П	P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter	Reel Width	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
	1,750	g				W1 (mm)	()	()	()	()	()	
SN74ALVTH162245GR	TSSOP	DGG	48	2000	330.0	24.4	8.6	15.8	1.8	12.0	24.0	Q1
SN74ALVTH162245LR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1
SN74ALVTH162245VR	TVSOP	DGV	48	2000	330.0	16.4	7.1	10.2	1.6	12.0	16.0	Q1

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*All dimensions are nominal

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Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALVTH162245GR	TSSOP	DGG	48	2000	346.0	346.0	41.0
SN74ALVTH162245LR	SSOP	DL	48	1000	346.0	346.0	49.0
SN74ALVTH162245VR	TVSOP	DGV	48	2000	346.0	346.0	33.0

DL (R-PDSO-G**)

48 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-118

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194

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